

arranged so as to match said first set of electrically conductive contacts when one of said individual elements is received in one of said receptors;

(g) applying an electrically conductive substance inside said receptors so as to cover at least the electrically conductive contacts on said bottom surface of said receptors, said electrically conductive substance exhibiting increased conductivity in a direction normal to said bottom of said receptors;

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(h) inclining said new substrate, with one end of said new substrate being higher than an opposite end of said new substrate;

(i) pouring freed individual elements onto the higher end of the surface of said new substrate having said receptors and shaking said new substrate so that free individual elements fall or roll down the inclined new substrate and are received in said receptors and said rings of said first set of electrically conductive contacts being brought into conductive contact with corresponding rings of said second set of electrically conductive contacts by the electrically conductive substance inside said receptors; and

(j) removing unreceived and/or improperly received individual elements which have fallen or rolled down to said opposite end of the inclined new substrate from said surface of said new substrate.

2. (Amended) The method of claim 1 further including the steps of:

(k) pouring said the unreceived and/or improperly received individual elements again onto said surface of said new substrate;

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(l) repeating said shaking followed by said step of removing until all said receptors are filled with said individual elements.

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3. The method according to Claim 1, wherein in said step of providing said original substrate, said release member comprises a release layer, a temporary carrier or a release tape.
  4. (Amended) The method according to Claim 1, wherein in said step of defining said individual elements, a shape of a conical frustum is achieved by a method comprising isotropic etching.
  5. (Amended) The method according to Claim 1, wherein in said step of fabricating said first set of electrically conductive contacts, said rings include a metal selected from a group comprising gold, aluminum, and titanium-tungsten.
  6. The method according to Claim 1, wherein in said step of providing said new substrate, said new substrate is made of a material selected from a group comprising semiconductor materials, glass, and plastic.
  7. (Amended) The method according to Claim 1, wherein in said step of providing said new substrate, said volume of each of said receptors is between about 5% to about 10% larger than said volume of each of said individual elements.
  8. (Amended) The method according to Claim 1, wherein in said step of fabricating said second set of electrically conductive contacts, said electrically conductive contacts include a metal selected from a group comprising gold, aluminum, and titanium-tungsten.
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9. (Amended) The method according to Claim 1, wherein said step of applying said electrically conductive substance includes applying and partially curing a unidirectionally conductive resin.

10. (Amended) The method according to Claim 9, wherein in said step of applying and partially curing said unidirectionally electrically conductive resin, said resin is applied by a method comprising steps of:

(a) coating said top surface of said new substrate and an inside area of said receptors with said unidirectionally electrically conductive resin; and

(b) removing said electrically conductive resin from said different substrate so that said unidirectionally electrically conductive resin remains only in said receptors.

11. (Amended) The method according to Claim 1, wherein in said step of inclining said new substrate inclines said substrate at an angle between about 30 degrees and about 60 degrees.

12. (Amended) The method according to Claim 1, wherein in said step of pouring and shaking of said freed individual elements, said shaking is achieved by applying vibrational or ultrasonic energy to said new substrate.

13. (Amended) The method according to Claim 1, wherein in said step of removing of said unreceived and/or improperly received individual elements, said removing is achieved with a use of motorized mechanical means.

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14. The method according to Claim 3, wherein said temporary carrier is attached to said original semiconductor substrate using a removable adhesive, said removable adhesive comprising a wax.

15. The method according to Claim 5, wherein said first set of electrically conductive contacts are fabricated by a method comprising metal deposition by evaporation and/or sputtering followed by etching using a photolithographic mask.

16. The method according to Claim 8, wherein said second set of electrically conductive contacts is fabricated by a method comprising deposition by evaporation and/or sputtering followed by etching using a photolithographic mask.

17. The method according to Claim 9, wherein said unidirectionally conductive resin is a Z-axis epoxy resin.

18. (Amended) The method according to Claim 1, further including a method for monitoring and correcting following said transferring of said individual elements, said method for monitoring and correcting comprising steps of:

(a) applying voltage pulse waveforms to said second set of electrically conductive contacts;

(b) measuring a current pulse generated as a result of said applying of said voltage pulse waveforms; and

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(c) repeating said steps of applying of said voltage pulse waveforms and of measuring of said current pulse with each receptor.

19. (Amended) The method according to Claim 18, further comprising, in case of absence of said current pulse, steps of:

(a) said shaking of said new substrate;

(b) said pouring of freed individual elements onto the higher end of the surface of said new substrate circuit elements;

(c) said removing of unreceived and/or improperly received individual elements;

(d) said applying of said voltage pulse waveforms;

(e) said measuring of said current pulse; and

(f) repeating said steps (a)-(e) until all said receptors are properly filled with said individual elements.

20. (Amended) The method according to Claim 19, wherein in said step of shaking of said freed individual elements, said shaking is achieved by applying vibrational or ultrasonic energy toward said original substrate.

21. (Amended) The method according to Claim 20, wherein in said step of removing of said unreceived and/or improperly received individual elements, said removing is achieved by

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use of motorized mechanical means.

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Please add the following new claims

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22. A method for fabricating electronics comprising:
- (a) freeing individual elements from a seed substrate; and
  - (b) using gravational forces and vibrational energy to place the individual elements in receptors formed in a different substrate.
23. The method of claim 22 wherein the individual elements are shaped as truncated cones and wherein the receptors are also shaped as truncated cones.
24. The method of claim 22 wherein the different substrate is of a different material composition than is the seed substrate.
25. The method of claim 22 wherein the using step includes lifting the different substrate so that the different substrate assumes an inclined attitude as an aid to the gravational forces in placing the individual elements in receptors formed in said different substrate.
26. The method of claim 22 wherein the individual elements include circuit elements formed therein.
27. The method of claim 26 wherein the circuit elements include a pixel.
28. The method of claim 22 further including forming electrical conductors on said individual elements which are arranged to contact matching electrically conductive contacts
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formed in the receptors.

29. The method of claim 28 further including applying an electrically conductive material inside said receptors so as to cover at least the electrically conductive contacts in said receptors, said electrically conductive material exhibiting increased conductivity in a direction normal a major surface of said different substrate.

30. The method according to Claim 22, wherein said step of applying said electrically conductive material includes applying and partially curing a unidirectionally conductive resin.

31. The method according to Claim 30, wherein in said step of applying and partially curing said unidirectionally electrically conductive resin, said resin is applied by a method including steps of:

(a) coating said top surface of said new substrate and an inside area of said receptors with said unidirectionally electrically conductive resin; and

(b) removing said electrically conductive resin from said different substrate so that said unidirectionally electrically conductive resin remains only in said receptors.

32. The method according to Claim 30, wherein said unidirectionally conductive resin is a Z-axis epoxy resin.

33. The method according to Claim 22, further including monitoring placement of said individual elements in said receptors, said method for monitoring and correcting comprising steps of:

(a) applying voltage pulse waveforms to selected ones of the electrically conductive

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